

**ABSTRACT**

Generally, a system and method for processing a substrate is provided. In one embodiment, a system for processing a substrate comprising a polisher, a first motion device, a second motion device and a load cup. The polisher has one or more polishing heads and one or more platens. The polishing heads are adapted to retain the substrate against the platens during processing and provide motion therebetween. The first motion device is disposed proximate the polisher's first side and moves along the first side between at least a first position and a second position. The second motion device is coupled to the first motion device and the load cup. The second motion device moves the load cup between at least a first position that is adjacent the first side and a second position that is inward of the first side.